HP 85081B High Impedance INPUT MODULE

Operating and Service Manual Insert

First Edition

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Operating and Service Manual Insert HP Part 85081-90013

Microfiche Operating and Service Manual Insert HP Part 85081-90014

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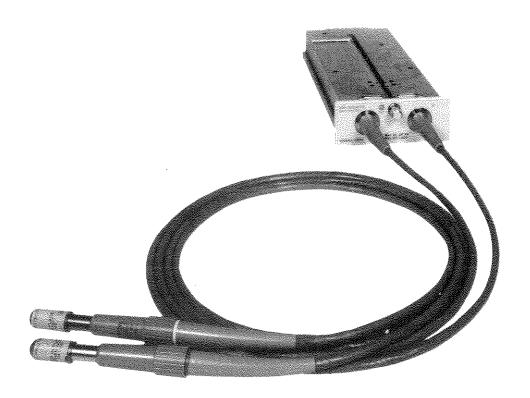


Figure 1-1. The HP 85081B High Impedance Input Module

General Information

Section 1

1-1 INTRODUCTION

This service manual contains information required to install, test, adjust and service the Hewlett-Packard Model 85081B High Impedance Input Probe. The HP 85081B High Impedance Input Probe is shown in Figure 1-1.

On the title page of this manual is a Microfiche Part Number. This number can be used to order 4 x 6 inch microfilm transparencies of the manual. Each microfiche contains up to 96 photo duplicates of the manual pages.

1-2 SPECIFICATIONS

Instrument specifications are listed in Table 1-2. These specifications are the performance standards or limits against which the instrument is tested. The specifications listed apply only when the HP 85081B is installed in either an HP 8508A Vector Voltmeter mainframe, or an HP 70138A MMS Vector Voltmeter Module.

1-3 ANTI-STATIC PRECAUTIONS

The printed circuit board contained in this instrument and the probes have components that are susceptable to damage by electrostatic discharge (ESD). To minimize the risks of damaging or decreasing the reliability of the instrument, the following procedures and cautions should be observed.

Static-free Workstation: All unpackaging and servicing should be carried out at a static-free workstation whenever practical.

De-soldering: When de-soldering components, ensure that the soldering iron is earthed. Always use a metalized solder remover.

Anti-Static Freezer Spray: When attempting to locate a temperature-related fault, use only an approved anti-static freezer spray.

Anti-Static Products: Table 1-1 contains details of anti-static products which are available from Hewlett-Packard.

Table 1-1. Anti-Static Products

Product	HP Part Number
Anti-static workstation kit	9300-0792
Metalized Solder Remover	8690-0227
Wrist-strap	9300-0970

1-4 INSTRUMENTS COVERED BY MANUAL

DATE CODE

The year and week of manufacture are stamped on the circuit board and also on the outer casing of the module. Example: "8-18" would indicate week 18 of 1988. There is no serial number.

SERIES CODE

A four-digit series number is contained on a serial number plate. This number should match the series number on the title page of this manual. An instrument manufactured after the printing of this manual may have a series number that is not listed on the title page. The unlisted series number indicates that the instrument is different from those described in this manual. The manual for this new instrument may be accompanied by a Manual Changes supplement. This supplement contains "change information" that explains how to adapt the manual to the new instrument.

In addition to change information, the supplement may also contain information for correcting errors in the manual. To keep this manual as current and as accurate as possible, Hewlett-Packard recommends that you periodically request the latest Manual Changes supplement. The supplement for this manual is identified by the manual print date and part number (both of which appear on the manual title page). Complimentary copies of the supplement are available from Hewlett-Packard. For information concerning a series number that is not listed on the page or in the Manual Changes supplement, contact your nearest Hewlett-Packard office.

1-5 DESCRIPTION

The Hewlett-Packard Model 85081B High Impedance Input Probe is a plug-in module for the HP 8508A Vector Voltmeter and the HP 70138A MMS Vector Voltmeter Module. The HP 85081B can measure signals in the frequency range 100kHz to 1GHz and at levels from 10uV to 1V. The HP 85081B has two high-impedance probes which can be used either alone or with accessories to make in-circuit measurements.

1-6 RECOMMENDED TEST EQUIPMENT

Table 1-1 in the HP 8508A Vector Voltmeter manual lists the test equipment required for testing, adjusting and servicing the HP 8508A Vector Voltmeter and the HP 85081B High Impedance Input Probe. Table 1-1 in the HP 70138A MMS Vector Voltmeter Service Manual lists the equipment required for testing and adjusting the HP 70138A MMS Vector Voltmeter and the HP 85081B High Impedance Input Probe. The Critical Specifications column describes the essential requirements for each piece of test equipment. Other equipment can be substituted if it meets or exceeds the critical specifications.

Table 1-2. Specifications

Specifications describe the instrument's warranted performance over the temperature range 0 to 55 deg C unless otherwise stated. Typical values describe typical, but non-warranted, performance. Nominal values are given as a guide to expected performance.

Measurement conditions:All specifications apply to measurements in a 50 ohm system and with autoranging off, unless otherwise stated. Measurements are made with the probes mounted in an HP 11536A Feedthru Tee unless otherwise stated.

Frequency Range

100kHz-1GHz

Maximum Input (damage level)

2V ac peak, ±50Vdc

Measurement Range

A and B Channel maximum

A (Ref) Channel minimum

Magnitude measurements

300mV, 100kHz-1MHz 1V, 1MHz-1GHz

Phase measurements

300mV, 100kHz-1GHz 10mV, 100kHz-300kHz 1mV,300kHz-3MHz 300uV,3MHz-1GHz

10uV rms, 1MHz-1GHz

B (Meas) Channel noise floor

Measurement bandwidth

1kHz (nominal)

Input Crosstalk

>100dB, 1MHz-500MHz >80dB, 500MHz-1GHz

Impedance

SWR<1.15, 100kHz-750MHz SWR<1.45, 750MHz-1GHz

Probe: 100kohm shunted by 2.5pF (nominal)

Probe with 11576A 10:1 Divider: 1Mohm shunted by 2pF (nominal) Probe with 10216A Isolator: 100kohm shunted by 5pF (nominal)

Magnitude Characteristics

Resolution: Accuracy:

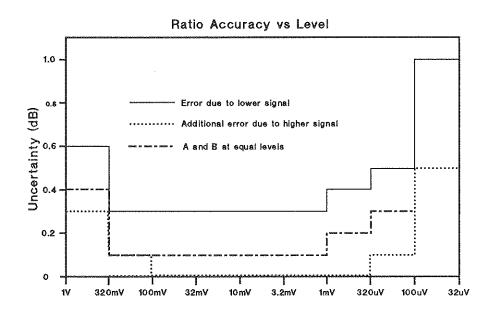
3 1/2 digits

Sum of Amplitude Accuracy vs Frequency and Absolute Accuracy vs Level or Ratio Accuracy vs Level (see following graphs).

Ratio Accuracy vs Level (1) (3)

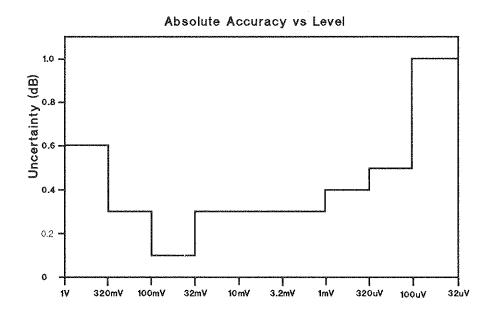
Add this term when making: Ratio measurements at any single frequency.

(Accuracy vs level is normally determined by the lower level signal. Noise (<320uV) and compression (>100mV) effects cause additional errors.)



Absolute Accuracy vs Level (1) (2) (3)

Add this term when making: Absolute measurements.

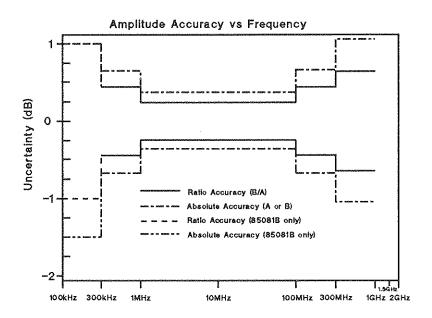


Amplitude Accuracy vs Frequency(1) (4) (A and B 100mV nominal)

Add this term when making: Absolute measurements. Ratio measurements over a frequency range.

Ignore this term when making:

Ratio measurements where the measurement is normalized to a reference at each new frequency.



Phase Characteristics

Display Range:

-179.9 to +180.0 degrees

Display Resolution:

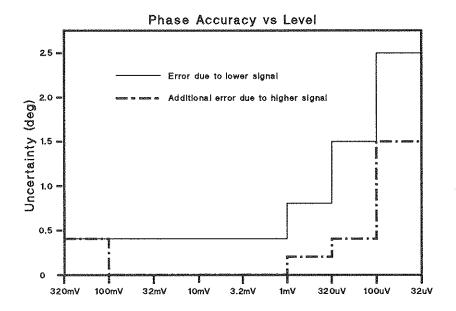
0.1 degrees

Accuracy:

Phase accuracy has two components - phase accuracy vs level and phase accuracy vs frequency. Add the uncertainty components from the following graphs using the information on each graph to decide if the uncertainty applies to the particular measurement.

Phase Accuracy vs Level (5) (6) (7)

Add this term when making: Phase measurements at any single frequency.

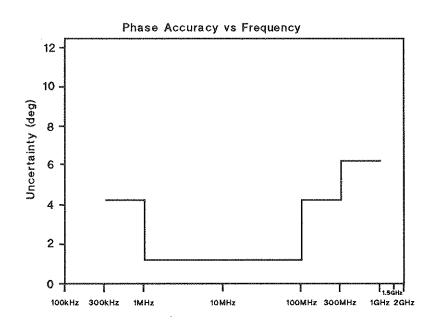


Phase Accuracy vs Frequency (5) (6) (A and B 100mV nominal)

Add this term when making: Phase measurements over a frequency range.

Ignore this term when making:

Phase measurements where the measurement is normalized to a reference at each new frequency.



Footnotes

- (1) 15 to 30 degrees C. Add ±0.1dB per 5 deg C outside this range.
- (2) A minimum input level depends on frequency. See Measurement Range.
- (3) Add ± 0.5 dB for signals above 100mV at frequencies greater than 500MHz.
- (4) A and B absolute value includes ±0.15dB source traceability error.
- (5) 15 to 30 degrees C. Add 1 deg per 5 deg C outside this range.
- (6) Add ±3 deg for signals above 100mV at frequencies greater than 500MHz.
- (7) Add ± 0.4 deg phase non-linearity for measurements other than 0 deg.

General

Search and lock time

Automatic tuning starts from lowest frequency and searches consecutive bands. Total search and lock time depends on the number of bands to be scanned and the lockup time within the selected band.

Process start time:

50ms after lock is lost.

Lockup (within 1 range):

40ms, frequencies up to 3MHz 20ms, frequencies greater than 3MHz

Ranges (MHz):

0.1-0.2, 0.2-0.6, 0.6-1, 1-3, 3-5, 5-8, 8-15, 15-25, 25-50, 50-80, 80-150, 150-250, 250-500, 500-1000, 1000-2000, 0.02-0.02.

Rear Panel Outputs:

Normal Operation: Provides an analog representation of the digital display values, including internal instrument correction factors.

OUTPUT 1 corresponds to DISPLAY 1, OUTPUT 2 corresponds to DISPLAY 2.

Range: 0 to ±1999 display counts.

Sensitivity: 1mV represents 1 display count (nominal).

For readings greater than ±1999 counts, the rear panel output voltage will remain fixed at ±2.0 Volts.

Display resolution can be controlled by manual ranging.

Update rate: Approximately 3 readings per second.

Direct Analog Output:Provides continuous direct output from the internal magnitude and phase detectors through 800Hz low-pass filters. No internal correction is applied.

OUTPUT 1 corresponds to linear magnitude (A or B selected by front panel control).

Sensitivity: 1V equals displayed full scale deflection (nominal). Can be controlled by manual ranging. OUTPUT 2 corresponds to B-A phase.

Sensitivity: 10mV per degree (nominal).

Phase Jitter: < 3 deg rms (typical, A=100mV, B=100uV)

HP-IB Capability

Interface functions:

Transfer Rate:

SH1 AH1 T6 TEO L4 LEO SR1 RL1 PPO DC1 DT1 CO

Normal Operation: Approximately 12 readings per second.

Measurement Conditions: Triggered measurement, default averaging.

Maximum Rate: Approximately 1 reading per 18ms.

Measurement conditions: Continuous output, averaging count 0, system format FP64, display rate off, equal steady state signals at A and B

inputs, single output of phase or linear A or B voltage.

General Information

Probe Power Supply

Supplies: +12 and -12 volts and ground

This supply is sufficient to operate 1 HP 85024A High Impedance Probe.

Environment

Temperature:

0 to 55 deg C (operating), -40 to 70 deg C (storage)

Humidity:

0 to 95%, non-condensing

Altitude:

0 to 4500m (operating), 0 to 15000m (storage)

RFI:

Conducted and radiated interference is within the requirements of

Messempfaenger-Postverfuegung 526/527/79.

Power:

100, 120, 220 or 240V +5/-10%, 48 to 440 Hz, 40VA

Size:

Std: 133mm (5.25in) H x 425.5mm (16.75in) W x 473.3mm (18.65in) D

Weight:

Std: 8.1kg (net) 11kg (shipping)

Installation Section 2

2-1 INTRODUCTION

This section provides installation instructions for the Hewlett-Packard Model 85081B High Impedance Input Probe. This section also includes information about initial inspection and damage claims, preparation for use, packaging, storage and shipment.

2-2 INITIAL INSPECTION

WARNING

IF THERE IS ANY SIGN OF SHIPPING DAMAGE TO THE INSTRUMENT, DO NOT INSTALL IN THE HP 8508A MAINFRAME, OR THE HP 70138A MMS MODULE. RETURN THE INSTRUMENT TO THE NEAREST HEWLETT-PACKARD OFFICE FOR CHECKING.

Inspect the shipping container for damage. If the shipping container or cushioning material is damaged, it should be kept until the contents of the shipment have been checked for completeness and the instrument has been checked mechanically and electrically. The Performance Tests check the complete specification of the instrument.

If the contents of the shipment are incomplete, if there is mechanical damage or defect, or if the instrument performance fails to meet specification, notify the nearest Hewlett-Packard office. If the shipping container is damaged or the cushioning material shows signs of stress, notify the carrier as well as the Hewlett-Packard office. Keep the shipping material for the carrier's inspection. The Hewlett-Packard office will arrange for repair or replacement at Hewlett-Packard's option without waiting for a claims settlement, providing that Hewlett-Packard and/or the carrier are notified within 12 days of shipment.

2-3 INSTALLING THE PROBE MODULE

The HP 85081B is installed in the opening on the front panel of the HP 8508A Vector Voltmeter or the HP 70138A MMS Vector Voltmeter. The HP 85081B should be carefully slid into the guides and pushed firmly to ensure the connectors are mated. The module should now be locked in place by turning the knob of the locking mechanism clockwise.

2-4 POWER REQUIREMENTS

The HP 85081B derives its power directly from the HP 8508A Vector Voltmeter mainframe or the HP 70138A MMS Vector Voltmeter.

2-5 OPERATING ENVIRONMENT

Temperature: The instrument may be operated in temperatures from 0° Centigrade to +50° Centigrade.

(Refer to the specifications for limitations.)

Humidity: The instrument may be operated with humidity up to 90% up to 40° Centigrade. However, the

instrument should also be protected from temperature extremes which may cause condensation

within the instrument.

Altitude: The instrument may be operated at altitudes up to 4600m (15000ft).

2-6 STORAGE AND SHIPMENT

Environment

The instrument may be stored or shipped in environments within the following limits:

Temperature: -40° Centigrade to +75° Centigrade.

Humidity: up to 90% at 65° Centigrade.

Altitude: 15300m (50000ft).

The instrument should also be protected from temperature extremes which may cause condensation within the instrument.

Packaging

Tagging for Service: If the instrument is being returned to Hewlett-Packard for service, please complete one of

the blue repair tags located at the front of this manual and attach it to the instrument.

Original Packaging: Containers and material identical to those used in the factory packing are available

through Hewlett-Packard offices. If the instrument is being returned to Hewlett-Packard for servicing, attach a tag indicating the type of service required, model number and full serial number. Also mark the container "FRAGILE" to ensure careful handling.

Other Packaging: The following general instructions should be used for re-packaging with commercially

available materials.

- (a) Wrap the instrument in heavy paper or plastic. (If shipping to Hewlett-Packard office or service centre, attach a tag indicating the type of service required, return address, model number and full serial number.)
- (b) Use a strong shipping container. A double-walled carton of 350-pound test material is adequate.
- (c) Use a layer of shock absorbing material 70mm to 100mm (3 to 4 inch) thick around all sides of the instrument to provide firm cushioning and prevent movement inside the container. Protect the control panel with cardboard.
- (d) Securely seal the shipping container.
- (e) Mark the shipping container "FRAGILE" to ensure careful handling.
- (f) In any correspondence, refer to the instrument by model number and date code.

Operation Section 3

3-1 INTRODUCTION

This information is contained in the HP 8508A Vector Voltmeter mainframe and HP 70138A MMS Vector Voltmeter manuals.

3-2 ESD PRECAUTIONS



Don't destroy your input probes!

The probes of the HP 85081B are susceptible to damage from electro-static discharge (ESD). Comply with the following precautions to help avoid damage to your probes.

Anti-static precautions

Never touch the tip of the probe.

Eliminate ESD on the body by wearing a snug-fitting ground strap that is connected to earth ground through a 1M ohm resistor.

Eliminate ESD on the work surface by using a grounded anti-static bench mat. Optional floor mats provide an extra measure of protection especially in areas with floor carpet. Never use this product on a carpeted work surface unless the carpet is of a conductive type specifically designed to eliminate ESD.

Do not introduce ESD into the Device Under Test (DUT) while using the probes. If an unprotected person touches a part of the DUT, a static surge could damage the DUT as well as the probes.

Always refit the protective cover when the probe is not in use.

Mechanical abuse

The tips of the probes are fragile and can break if the probe is dropped.

Performance Tests

Section 4

4-1 INTRODUCTION

The Performance Test procedures in this section of the manual test the instruments electrical performance using the specifications listed in Table 1-2 of this manual as the performance standard. These specifications apply equally when the HP 85081B is used in either the HP 8508A or the HP 70138A Vector Voltmeter.

In the event of failure, refer to the Troubleshooting information in section 8 of this manual, except where specific reference is made to the Adjustment Procedures in section 5.

Power-on Checks

The Power-on Checks are performed automatically at switch-on. These checks test the operation of the mainframe processor, the functionality of the measurement modes and the presence of the HP 85081B Input Module. The Power-on Checks are part of the self-test routine used for operational verification.

Failure of these tests results in an Error Code number being displayed. Errors relating to the HP 85081B are in the 600 Series.

Performance Tests

The Performance Tests verify that the instrument is operating within the limits of the full specification. It should be noted, however, that the specifications apply to measurements in a 50 ohm system with the autoranging off.

In the event of a performance test failure, the test should be repeated with manual range selection and a check made of Adjustment Procedures and, if necessary, the Troubleshooting section.

4-2 TEST EQUIPMENT REQUIRED

Equipment required for the Performance Tests is listed in Table 1-1 in the HP 8508A or HP 70138A Vector Voltmeter manual. Any equipment which meets or exceeds the critical specifications may be substituted for the recommended model.

4-3 TEST RECORDS

The results of the Performance Tests may be recorded in Tables 4-2 to 4-9. The Test Records list all of the tested specifications and their acceptable limits. The results recorded at incoming inspection can be used for comparison in periodic maintenance and troubleshooting after repair or calibration.

4-4 CALIBRATION CYCLE

This instrument requires periodic verification of performance. Depending upon the use and environmental conditions, the instrument should be checked using the Performance Tests at yearly intervals.

4-5 PERFORMANCE TESTS

The Performance Test procedures provide a complete check of the instrument's electrical performance using the specifications listed in Table 1-2 as the performance standard. Table 4-1 gives a complete list of the Performance Tests. If any of the Performance Tests are out of specification, refer to section 5 of this manual and the appropriate Vector Voltmeter manual. If, after adjustment, the Specifications still cannot be met, refer to section 8 of this manual.

Table 4-1. Performance Tests

Test Title	Paragraph Number
Isolation between Channels (Input Crosstalk)	4-7
Reference Channel Lock Level and Channel B Noise Floor	4-8
Phase Accuracy vs Frequency	4-9
Amplitude Accuracy vs Frequency	4-10
Phase Accuracy vs Level	4-11
Phase Offset Accuracy	4-12
Voltage Ratio Accuracy vs Level	4-13
Amplitude Accuracy vs Input Level (and rear panel output check)	4-14

4-6 WARM-UP TIME

The instrument must be switched on for a minimum of 30 minutes before carrying out any tests. Once the instrument's operating temperature has stabilized, perform an automatic internal system calibration by selecting [SHIFT] [CAL TEST] on the HP 8508A or [Misc] [CAL] on the HP 70138A MMS system.

4-7 ISOLATION BETWEEN CHANNELS (INPUT CROSSTALK)

SPECIFICATIONS:

Input Crosstalk:

1 MHz - 500 MHz > 100 dB

500 MHz - 1 GHz > 80 dB

DESCRIPTION:

Crosstalk is defined as the leakage interference between the instrument input channels. Crosstalk is tested by observing the signal level on a terminated input while applying a signal to the other input.

In this procedure, a maximum level signal of 1Vrms is applied to the Channel A input of the HP 85081B Input Module while the Channel B input is terminated in 50 ohms.

The crosstalk from Channel A to Channel B is indicated by an amplitude ratio measurement in DISPLAY 1.

EQUIPMENT:

Instrument	Critical Specification	on	Recommended Model
Signal Source	Frequency Range Amplitude	1.0 -1000 MHz 1.0 V rms	HP 8642B
50 Ohm Tee (2) 50 Ohm Termination (2))		HP 11536A HP 909C

PROCEDURE:

1. Configure the equipment as shown in Figure 4-1.

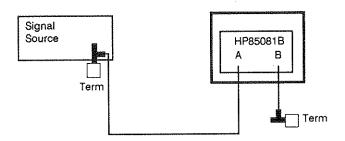


Figure 4-1. Channel Isolation Test Setup

2. Signal Source setup:

Frequency:

1.0 MHz

Amplitude:

1.0 V rms

3. HP 8508A setup

HP 70138A setup

Function

[PRESET]

[I-P]

Instrument preset

[B/A MAG]
[DISPLAY] dB

[Mag/Ph Measure] [B/A MAG]

[Format Functn][dB]

B/A ratio measurement in dB, in

DISPLAY 1.

[LOCK RANGE]

[SHIFT] [VIEW RANGE]
"up"/"down" arrow keys

to select 1-3MHz.

[Lock Range] [1.0 - 3.0MHz]

Set frequency range.

[LOCK RANGE]

[Lock Range] [AUTO LOCK]

Unlock frequency range.

[SHIFT] [CAL/TEST]

[Misc] [CAL]

Self calibration.

- 4. Note the value obtained for the Input Isolation in DISPLAY 1 and record this value in the Performance Test Record (which is located at the end of the Performance Tests section.)
- 5. Repeat this procedure for each frequency noted in the Performance Test Record.

Should the results in any particular frequency range fall outwith the specification limits, the test should be repeated with the instrument locked in the appropriate frequency range. The process for locking the frequency range is shown below.

The instrument can be locked into a particular frequency range as follows:

HP 8508A

HP 70138A

[LOCK RANGE]

[Lock Range] [required frequency range]

[SHIFT] [VIEW RANGE] "up"/"down" keys to select frequency range.

[LOCK RANGE]

[Lock Range] [AUTO LOCK]

Note: The frequency points in the Performance Test Record are a minimum requirement as they have been selected to coincide with the specification needs and ranges of the instrument.

4-8 REFERENCE CHANNEL LOCK LEVEL AND CHANNEL B NOISE FLOOR

SPECIFICATIONS:

Reference Channel Lock Level: 10.0 mV, 0.1 MHz - 0.3 MHz.

1.0 mV, 0.3 MHz - 3.0 MHz. 0.3 mV, 3.0 MHz - 1.0 GHz.

10 uV rms, 1MHz - 1GHz.

DESCRIPTION:

Channel B Noise Floor:

In this procedure, Channel B is terminated in 50 ohms and the minimum signal amplitude (appropriate to the frequency), is applied to the reference channel (Channel A). The channel should then be locked onto this signal.

The noise floor is defined with the minimum signal applied to Channel A while Channel B is terminated in 50 ohms.

EQUIPMENT:

Instrument	Critical Specification		Recommended Model
Signal Source	Frequency Range Amplitude	0.1MHz - 1GHz -47dBm	HP 8642B
50 Ohm Probe Tee (2) 50 Ohm Termination (2)	1		HP 11536A HP 909C

PROCEDURE:

1. Configure the test equipment as in Figure 4-2.

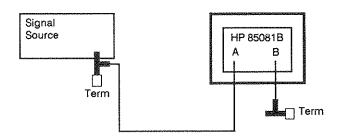


Figure 4-2. Test Setup for Reference Channel Lock Level and Channel B Noise Floor

2. Signal Source setup.:

Frequency:

100 kHz

Amplitude:

10 mV rms

3. HP 8508A setup

HP 70138A setup

Function

[PRESET]

[I-P]

Instrument preset.

[B]

[Mag/Ph Measure]

[DISPLAY 2] [B]

'Input Level in DISPLAY 1
Noise Floor in DISPLAY 2.

[SHIFT] [CAL/TEST]

[Misc] [CAL]

Self calibration.

- 4. Check that Channel A is locked (indicated by the UNLOCKED LED being extinguished).
- 5. Adjust the signal generator output level and frequency in the sequence shown in the Performance Test Record. Check the status of the UNLOCKED LED and note the noise floor readings and enter them in the Performance Test Record (which is located at the end of the Performance Tests section.)
- 6. Repeat this procedure for each frequency defined in the Performance Test Record and note the Noise Floor Level and the lock status at each step.

Should the results in any particular frequency range fall outwith the specification limits, the test should be repeated with the instrument locked in the appropriate frequency range. The process for locking the frequency range is shown below.

The instrument can be locked into a particular frequency range as follows:

HP 8508A

HP 70138A

[LOCK RANGE]

[Lock Range] [required frequency range]

[SHIFT] [VIEW RANGE] "up"/"down" keys to select frequency range.

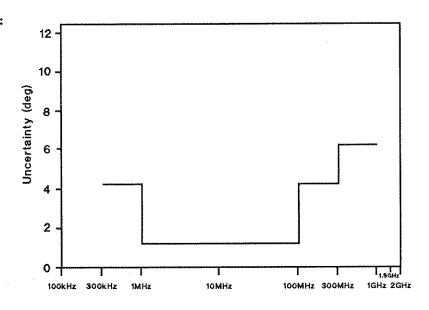
[LOCK RANGE]

[Lock Range] [AUTO LOCK]

Note: The frequency points in the Performance Test Record are a minimum requirement as they have been selected to coincide with the specification needs and frequency ranges of the instrument.

4-9 PHASE ACCURACY vs FREQUENCY

SPECIFICATIONS:



DESCRIPTION:

In this test, the Phase Uncertainty is tested at the reference level of 100mV and zero phase through the frequency range of the instrument, from 300kHz to 1GHz.

The test looks at the phase difference in the phase tracking of the two channels and includes the probe and probe cable tracking error.

EQUIPMENT:

Instrument	Critical Specification		Recommended Model
Signal Source	Frequency Range Amplitude	0.3 - 1000MHz 100 mV	HP 8642B
Power Divider	DC - 4 GHz		
	Ins Loss: 6 dB		HP 11636A
	O/P Tracking	< = $0.4 dB$	
	Phase Tracking	0.2 deg or better.	
50 Ohm Probe Tee (2)			HP 11536A
50 Ohm Termination (2)			HP 909C
10dB Attenuator (2)			HP 8491A/B

PROCEDURE:

1. Configure the equipment as shown in Figure 4-3 and connect the attenuators directly to the power divider outputs. Connect the probe tees directly to the attenuators and ensure that the probes are firmly located.

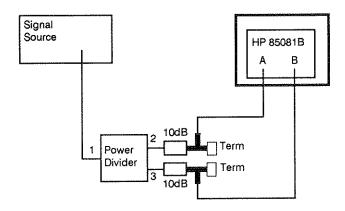


Figure 4-3. Phase Accuracy vs Frequency Test Setup

2. Signal Source setup:

Frequency:

1.0 MHz

Amplitude:

640mV (This will produce a nominal 100mV at the ouput of the

10dB attenuator.)

3: HP 8508A setup

HP 70138A setup

Function

[PRESET]

[I-P]

Instrument preset.

[B-A PHASE]

[Mag/Ph Measure]

[DISPLAY 2] [B-A PHASE]

Amplitude in DISPLAY 1

Phase in DISPLAY 2.

[LOCK RANGE]

[SHIFT] [VIEW RANGE] "up"/"down" keys to

select 1-3MHz

[Lock Range] [1.0 - 3.0MHz]

Set frequency range.

[LOCK RANGE]

[Lock Range] [AUTO LOCK]

Unlock frequency range.

[SHIFT] [CAL/TEST]

[Misc] [CAL]

Self calibration.

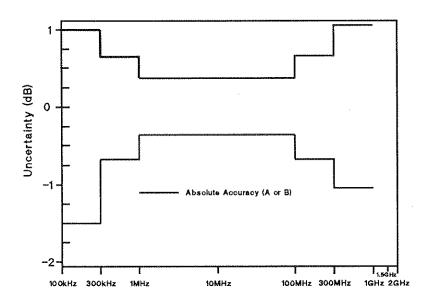
4. With the output level unchanged, vary the frequency in the sequence shown in the Performance Test Record and record the phase reading at each step. The Performance Test Record is located at the end of the Performance Test section.

- 5. Connecting the probe tees directly to the 10dB attenuator outputs minimizes differences due to electrical path lengths. These differences can lead to significant phase measurement errors. For any frequency point that may be out of limits, this source of error should be balanced out by using manual range selection in conjunction with the following notes.
- a) Repeat the measurement as previously detailed and make a note of the phase lag or lead.
- b) Interchange the two probes, without disturbing the rest of the test setup.
- c) Make a note of this new value of phase lag or lead.
- d) These two measurements should be summed and the result divided by two. This result is the phase error due to the HP 85081A and should be deducted from the phase readings obtained.
- e) Repeat this process for any frequency noted as being out of specification.

Note: At frequencies above 500MHz, rotating the probes in the Tees, or introducing sharp bends in the probe cables, may produce variations in the order of 1 degree.

4-10 AMPLITUDE ACCURACY vs FREQUENCY

SPECIFICATION:



DESCRIPTION:

The voltage amplitude accuracy is measured with the channel input level set to -7.0dBm ± 0.1 dBm at each frequency point being checked.

The signal level is checked with the power meter and care must be taken to ensure that the power meter calibration factor is corrected for the frequency being used.

To allow measurement of Channel B, a power splitter is used to divide the signal and provide a lock reference to Channel A.

EQUIPMENT:

Instrument	Critical Specification		Recommended Model
Signal Source	Frequency Range Amplitude	0.1 - 1000 MHz 100mV	HP 8642B
Power Divider	•		HP 11636A
50 ohm Tee (2)			HP 11536A
50 Ohm Termination (2)			HP 909C
N(m)-N(m) Cable			HP 11500A/B
RF Power Meter	Accuracy	± 0.02 dB	HP 436A/HP 438A
	Power Ref NBS Traceable.	50MHz 1.00mW	
Power Sensor			HP 8482A
Adapter N(f) - N(f)			HP 1250-0777
10dB Attenuator (2)			HP 8491A/B

PROCEDURE:

1. Configure the equipment as shown in Figure 4-4 step (a), with the power sensor connected to the 10dB attenuator which is connected to port 2 of the power splitter; and Channel B of the HP 85081B connected via the 50ohm Tee to the 10dB attenuator which is connected to port 3 of the power splitter.

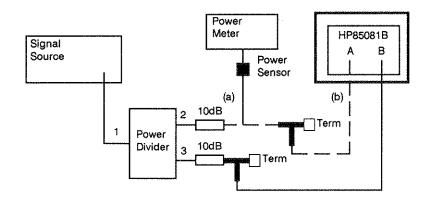


Figure 4-4. Voltage Accuracy Equipment Setup

2. Signal Source setup:

Frequency:

1 MHz.

Amplitude:

9 dBm. To produce a power meter reading of -7.0 dBm, ±0.1dB

at the outputs of the 10dB attenuators.

- 3. Record the power meter reading in the Performance Tests Results table at the rear of this section.
- 4. Reconfigure the equipment as shown in Figure 4-4 step (b), with Channel A of the HP 85081B connected (via the 500hm Tee) to the output of the 10dB attenuator, which is connected to port 2 of the power splitter.

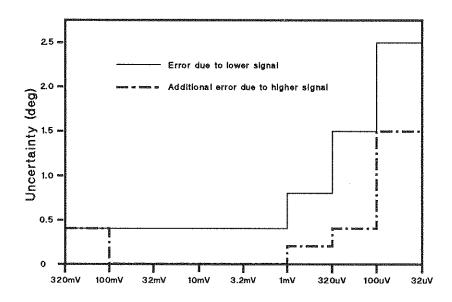
5.	HP 8508A setup	HP 70138A setup	Function
	[PRESET]	[I-P]	Instrument preset.
	[B]	[Mag/Ph Measure] [DISPLAY 2] [B]	'A' voltage in DISPLAY 1 'B' voltage in DISPLAY 2.
	[POWER MEAS] [DISPLAY] dB	[Format Functn] [dB]	dBm display.
	[LOCK RANGE] [SHIFT] [VIEW RANGE] "up"/"down" arrow keys to select 1-3MHz	[Lock Range] [1.0 - 3.0 MHz]	Select frequency range.
	[LOCK RANGE]	[Lock Range] [AUTO LOCK]	Unlock frequency range.
	[SHIFT] [CAL/TEST]	[Misc] [CAL]	Self calibration.

- 6. Record the DISPLAY 1 reading in the Performance Tests Results table.
- 7. Interchange the probe connections and record the value of the DISPLAY 2 reading in the Performance Tests Results table.
- 8. Repeat the entire test for each frequency point required.

NOTE: Ensure that you set the power meter calibration factors to the value appropriate to the frequency being used.

4-11 PHASE ACCURACY vs LEVEL

SPECIFICATIONS:



DESCRIPTION:

This test is a measure of the instrument's ability to measure phase as the signal level is varied. This is a function of the IF performance. This test can be repeated for other frequencies as required.

EQUIPMENT:

Instrument	Critical Specification		Recommended Model
Signal Source	Frequency Range Amplitude	0.3 - 13MHz 19dBm	HP 8642B
Power Divider	DC - 4 GHz		HP 11636A
	Ins Loss	6 dB	
	O/P Tracking	< = 0.4 dB	
	Phase Tracking	2 deg or better	
Attenuator (2)	0-110 dB in 10 dB	steps.	HP 8496A/G Opt 890*
Attenuator Driver	Required for HP 8	8496G	HP 11713A**
50 Ohm Probe Tee (2)			HP 11536A
50 Ohm Termination (2))		HP 909C
N(m) - N(m) Cable			HP 11500A/B
Adapter N(f) - N(f)			HP 1250-0777

^{*}Calibration required at 30MHz.

NOTE: The construction of the HP 8496 attenuator series is such that the change in electrical length (phase response) as attenuator sections are switched in and out is substantially less than the HP 85081B specifications. This may not be the case if different attenuators are substituted.

^{**} Required if HP 8496G programmable attenuator is used.

PROCEDURE:

1. Configure the Test Equipment as shown in Figure 4-5 with the power splitter and probe tees connected directly to the attenuator.

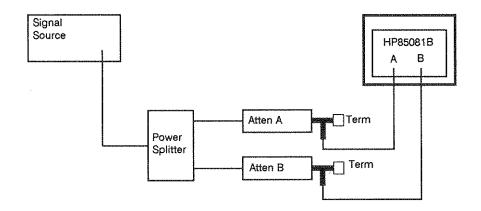


Figure 4-5. Phase Accuracy vs Level Test Setup

- 2. Set both attenuators to 20 dB.
- 3. Signal Source setup:

		Freque: Amplit	•	1 MHz +19dBm	
4.	HP 8508A setup		HP 70138A	setup	Function
	[PRESET]		[I-P]		Instrument preset.
	[B-A PHASE]		[Mag/Ph M [DISPLAY 2	leasure] 2] [B-A PHASE]	Amplitude in DISPLAY 1 Phase in DISPLAY 2.
	[LOCK RANGE] [SHIFT] [VIEW RA "up"/"down" arrow k to select 1-3MHz		[Lock Ranç	ge] [1.0 - 3.0 MHz]	Select frequency range.
	[LOCK RANGE]		[Lock Ranç	ge] [AUTO LOCK]	Unlock frequency range.
	[SHIFT] [CAL/TES	ST]	[Misc] [CA	L]	Self calibration.
	[SHIFT] [SAVE RE	F	[Ref] [SAVI	E REF]	Normalize system.

- 5. Note the Phase reading in Display 2 and record this in the Performance Test Table which is located at the end of the Performance Tests section.
- 6. Repeat this process for the attenuator settings defined in the Performance Test Record and note the phase reading at each step.

4-12 PHASE OFFSET ACCURACY

SPECIFICATIONS:

The linearity of phase offset from 0 degrees is ± 0.4 degrees.

DESCRIPTION:

In this test, the channels are set up for a nominal level of 100mV, at a frequency of 1.0MHz. The phase between the two channels is then varied.

EQUIPMENT:

Instrument	Critical Specification		Recommended Model
Signal Source	Dual Channel Synthesizer		HP 3326A
O .	Frequency Range Amplitude 100mV	dc-13 MHz	
	Phase Offset Accuracy	±0.3 Deg	
50 Ohm Probe Tee (2))		HP 11536A
50 Ohm Termination			HP 909C
Adaptor N(f) to BNC			HP 1250-0077

PROCEDURE:

1. Configure the equipment as shown in Figure 4-6, with the probe tees connected directly to the source output via the adaptors.

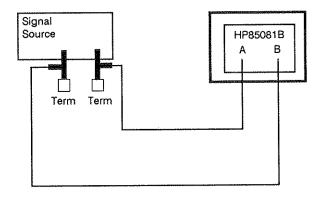


Figure 4-6. Phase Offset Accuracy Setup

2. Signal Source Setup:

Frequency:

1 MHz on both channels.

Amplitude:

100mV rms on both Channels.

Phase Offset:

Zero.

3. HP 8508A setup

HP 70138A setup

Function

[PRESET]

[I-P]

Instrument preset.

[B-A PHASE]

[Mag/Ph Measure]

[DISPLAY 2] [B-A PHASE]

Amplitude in DISPLAY 1

Phase in DISPLAY 2.

[LOCK RANGE]

[SHIFT] [VIEW RANGE]
"up"/"down" arrow keys

to select 1-3MHz

[Lock Range] [1.0 - 3.0MHz]

Set frequency range.

[LOCK RANGE]

[Lock Range] [AUTO LOCK]

Unlock frequency range.

[SHIFT] [CAL/TEST]

[Misc] [CAL]

Self calibration.

[SHIFT] [SAVE REF]

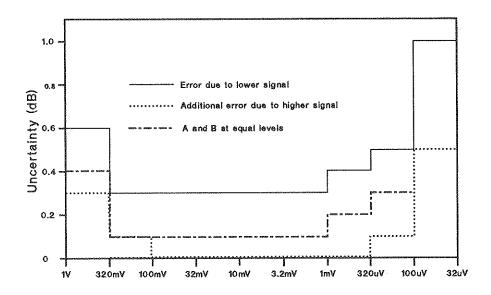
[Ref] [SAVE REF]

Normalize system.

^{4.} With the frequency and level unchanged, vary the signal source phase offset between the channels as defined in the Performance Test Record and note the instrument reading at each step. The Performance Test Record is located at the end of the Performance Test section.

4-13 VOLTAGE RATIO ACCURACY vs LEVEL

SPECIFICATION:



DESCRIPTION:

The voltage ratio accuracy is tested by applying known signal levels and comparing these with the results displayed by the Vector Voltmeter.

EQUIPMENT:

Instrument	Critical Specif	ication	Recommended Model
Signal Source 50 Ohm Tee (2)	Dual Channel	+13dBm per channel	HP 3326A HP 11536A
50 Ohm Termination (2	2)		HP 909C
Attenuator (2)	0 to 110 dB in	10 dB steps.	HP 8496A/G Opt 890*
Attenuator Driver			HP 11713A**
BNC(m)-BNC(m) Cab	le(2)		HP 8120-1839
Adapter N(m)-BNC(f)			HP 1250-0780
Power Meter	Accuracy	±0.02dB	HP 436A/HP438A
	Ref Output	50 MHz 0.0 dBm	
	Traceable to N	IBS	
Power Sensor			HP 8482A

^{*} Calibration data required.

^{**} Required if HP 8496G programmable attenuator is used.

PROCEDURE:

1. Configure the Test equipment as shown in Figure 4-7.

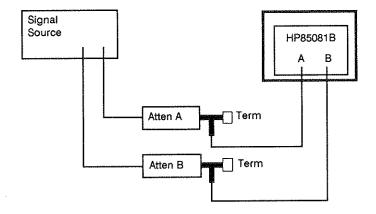


Figure 4-7. Voltage Ratio Accuracy Test Setup

- 2. Set both attenuators to 20dB.
- 3. Set both channels of the signal source as follows:

Frequency:

1MHz.

Amplitude:

+13dBm.

- 4. Measure the signal source output level with the power meter, to verify an output level of ± 0.1 dB. Adjust the source level as necessary, to achieve this.
- 5. HP 8508A setup

HP 70138A setup

Function

[PRESET]

[I-P]

Instrument preset.

[B/A MAG]
[DISPLAY] dB

[Mag/Ph Measure] [B/A MAG] [Format Functn] [dB] B/A ratio measurement, in dB,

in DISPLAY 1.

[SHIFT] [CAL/TEST]

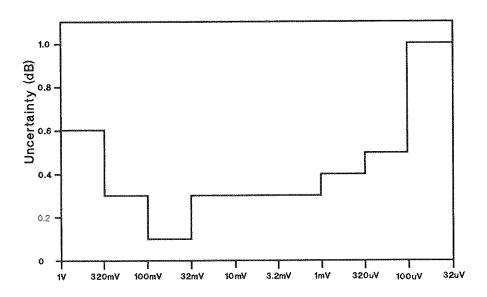
[Misc] [CAL]

Self calibration.

- 6. Enter the corrected attenuator figures in the Performance Test Table (which is located at the end of the Performance Tests section).
- 7. Vary the attenuator settings as shown in the Performance Test Table and note the channel readings at each step.
- 8. Calculate the actual errors and check for compliance with the instrument specification.

4-14 AMPLITUDE ACCURACY vs INPUT LEVEL (and rear panel output check)

SPECIFICATIONS:



DESCRIPTION:

The amplitude accuracy is tested by applying known signal levels and comparing these with the results displayed by the Vector Voltmeter.

Rear panel output signals are checked for a nominal sensitivity of 1mV per display count.

EQUIPMENT:

Instrument	Critical Specific	cation	Recommended Model
Signal Source	Dual Channel (+13dBm per channel)	
50 Ohm Tee (2)			HP 11536A
50 Ohm Termination (2)			HP 909C
Attenuator (2)	0 to 110dB in 10)dB steps	HP 8496A/G Opt890*
Attenuator Driver	Required for H	P 8496G	HP 11713A**
BNC(m)-BNC(m) Cable	•		HP 8120-1839
Adaptor N(m)-BNC(f)(2			HP 1250-0780
Power Meter	Accuracy	±0.02dB	HP 436A/HP 438A
	Ref Output	50MHz, 0.0dBm	
	Traceable to NI	BS	
Power Sensor			HP 8482A
DVM			HP 3456A

^{*} Calibration data required.

^{**} Required if HP 8496G programmable attenuator is used.

PROCEDURE:

1. Configure the equipment as shown in Figure 4-8.

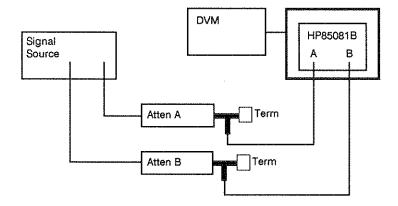


Figure 4-8. Amplitude Accuracy vs Input Level (and rear panel output check) Test Setup

- 2. Set both attenuators to 20dB.
- 3. Set both channels of the signal source as follows:

Frequency: 1MHz Amplitude: +13dBm

- 4. Measure the signal source output level with the power meter to verify an output level of $\pm 0.1 dBm$ on each channel. Adjust the source output level as necessary to achieve this result.
- 5. HP 8508A setup Function HP 70138A setup PRESET [I-P] Instrument preset. [B][POWER MEAS] [Mag/Ph Measure] [DISPLAY 2] [B] [Format Functn] [dB] [DISPLAY] dB Set up for dBm in both displays. [SHIFT] [CAL/TEST] [Misc] [CAL] Self calibration. [SHIFT] [SAVE REF] [Ref] [SAVE REF] Normalize system.
- 6. Vary the attenuator settings as shown in the Performance Test Table and note the channel readings at each step. Check that these are within the permitted tolerance.

Note the value of the appropriate rear panel output. This has a nominal sensitivity of 1mV per display count.

7. Repeat step 6 for Channel B.

4-15 SWR MEASUREMENT

SPECIFICATIONS:

SWR < 1.15	100kHz to 750MHz	(Return loss = -23dB)
SWR < 1.45	750MHz to 1.0GHz	(Return loss = -14.7dB)

DESCRIPTION:

The SWR of each input is measured over the operating frequency range 100kHz to 1.0GHz.

EQUIPMENT:

Instrument	Critical Specification	Recommended Model
Network Analyzer		HP 8753A/B/C
S Parameter Test Se	t	HP 85046A
Phase Matched Cab	les	HP 11851B
50 ohm Tee (2)		HP 11536A
50 ohm Termination	(2)	HP 909C

PROCEDURE:

1. Connect the equipment as shown in Figure 4-9.

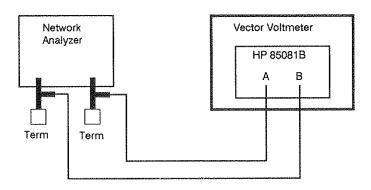


Figure 4-9. SWR Measurement Setup

- 2. Set up the Network Analyzer for SWR measurement.
- 3. Measure the SWR over the frequency range 100kHz to 1GHz and record the results in the Performance Test Record (which is contained at the end of the Performance Tests section).

Table 4-2. Performance Test Record (1 of 9)

Paragraph 4-7

ISOLA	TION BETWEEN	CHANNELS (INPUT	CROSSTALK)	
Frequency Range (MHz)	Frequency (MHz)	Isolation (dB in A)	Specification	
1.0-3.0	1.0	the control of the co	> -100 dB	
3.0-5.0	4.0		> -100 dB	
5.0-8.0 8.0-15.0	6.5 11.5		> -100 dB > -100 dB	
15.0-25.0	20.0		> -100 dB	
25.0-50.0	35.0		> -100 dB	
50.0-80.0	50.0		> -100 dB	
50.0-80.0	65.0		> -100 dB	
80.0-150.0	115.0		> -100 dB	
150.0-250.0	200.0		> -100 dB	
250.0-500.0	400.0		> -100 dB	
500.0-1000.0	750.0		> -80 dB	
500.0-1000.0	1000.0		> -80 dB	

Table 4-3. Performance Test Record (2 of 9)

Paragraph 4-8

REFERENCE	CHANNEL LOC	K LEVEL AND	CHANNE	EL B NOISE	FLOOR	
Frequency Range (MHz)			Lock OK?	Noise F Measured	loor Maximum	
0.1-0.2 0.1-0.2	0.1 0.15	10.0 10.0	<u>kontrolitionos</u>		N/A N/A	
0.2-0.6	0.4	1.0			N/A	
0.6-1.0	0.8	1.0		***************************************	N/A	
1.0-3.0	1.0	1.0			10uV rms	
3.0-5.0	4.0	0.3			10uV rms	
5.0-8.0	6.5	0.3			10uV rms	
8.0-15.0	11.5	0.3			10uV rms	
15.0-25.0	20.0	0.3			10uV rms	
25.0-50.0	35.0	0.3			10uV rms	
50.0-80.0	50.0	0.3			10uV rms	
50.0-80.0	65.0	0.3			10uV rms	
80.0-150.0	115.0	0.3			10uV rms	
150.0-250.0	200.0	0.3		***************************************	10uV rms	
250.0-500.0	400.0	0.3		***************************************	10uV rms	
500.0-1000.0	750.0	0.3		***************************************	10uV rms	
500.0-1000.0	1000.0	0.3		EACHDOACHUMMACORDOCH	10uV rms	

Table 4-4. Performance Test Record (3 of 9)

PHASE AC	CURACY vs FRE	EQUENCY at Referer	nce Level
Frequency Range (MHz)	Frequency (MHz)	Phase Reading (DISPLAY 2)	Tolerance
0.2-0.6 0.6-1.0 1.0-3.0 3.0-5.0 5.0-8.0 8.0-15.0 15.0-25.0 25.0-50.0 50.0-80.0 80.0-150.0 150.0-250.0 250.0-500.0 500.0-1000.0 500.0-1000.0	0.3 0.8 1.0 4.0 6.5 11.5 20.0 35.0 50.0 65.0 115.0 200.0 400.0 750.0 1000.0		± 4.2 Deg ± 4.2 Deg ± 1.2 Deg ± 4.2 Deg ± 4.2 Deg ± 6.2 Deg ± 6.2 Deg ± 6.2 Deg

Table 4-5. Performance Test Record (4 of 9)

AMPLITUDE ACCURACY vs FREQUENCY							
Frequency (MHz)	Power Meter Reading (M) (dBm)	Display 1	Reading 2	Error Channel A (M-1)		Limits	
0.300 1.000 10.000 50.000 100.000 300.000 700.000 1000.000						±0.65 ±0.35 ±0.35 ±0.35 ±0.35 ±0.65 ±1.0 ±1.0	

Table 4-6. Performance Test Record (5 of 9)

PHASE ACCURACY vs LEVEL								
Attenuator A Setting	Attenuator B Setting	Channel A Input Level	Channel B Input Level	Phase Reading	Tolerance (Degrees			
20 dB	20 dB	100mV	100mV	***************************************	0			
20 dB	0 dB	100mV	1000mV		±1.3			
20 dB	10 dB	100mV	320mV		±0.8			
20 dB	30 dB	100mV	32mV		±0.3			
20 dB	40 dB	100mV	10mV		±0.3			
20 dB	50 dB	100mV	3.2mV		±0.3			
20 dB	60 dB	100mV	1.0mV	***************************************	±0.8			
20 dB	70 dB	100mV	320uV		±1.1			
0 dB	20 dB	1000mV	100mV		±1.3			
10dB	20dB	320mV	100mV		±0.8			
30dB	20dB	32mV	100mV		±0.8			
40dB	20dB	10mV	100mV		±0.8			
50dB	20dB	3.2mV	100mV		±0.8			
60dB	20dB	1.0mV	100mV		±0.8			
70dB	20dB	320uV	100mV		±1.1			

Table 4-7. Performance Test Record (6 of 9)

Paragraph 4-12

PHA	SE OFFSET ACCU	RACY	
Signal Source Phase Offset (Deg)	Vector Voltmeter Phase Reading (DISPLAY 2)	Display Error	Tolerance (Degrees)
+ 180 + 150 + 120 + 90 + 30 000 - 30 - 90 - 120 - 150 - 180			±0.4 ±0.4 ±0.4 ±0.4 ±0.00 ±0.4 ±0.4 ±0.4 ±0.4

Table 4-8. Performance Test Record (7 of 9)

	VOLTAGE	E RATIO ACC	CURACY vs L	EVEL (for Le	evel A = Lev	vel B up to 30	0MHz)	
Nominal I/P Level	Atten A Setting (dB)	Atten B Setting (dB)	Atten A Actual * A	Atten B Actual * B	(B-A) Actual (R)	Display Reading (D)	Error (D-R)	Spec (dB)
100mV	20	20						±0.1
320mV	10	10						±0.4
1000mV	0	0						±0.4
32mV	30	30					***************************************	±0.1
10mV	40	40						±0.1
3.2mV	50	50						±0.1
1.0mV	60	60		***************************************				±0.2
320uV	70	70						±0.3

^{*} Data from Calibration Certificate.

Nom I/P L		Atten A Setting	Atten B Setting	Atten A Actual *	Atten B Actual *	(B-A) Actual	Display Reading	Error (D-R)	Spec (dB)
Α	В	(dB)	(dB)	Α	В	(R)	(D)		
100mV	100mV	20	20		***************************************				±0.3
100mV	32mV	20	30						±0.4
100mV	10mV	20	40				4-11-12-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-1-	<u> </u>	±0.4
100mV	3.2mV	20	50	***************************************					±0.4
100mV	1.0mV	20	60			X			±0.4
100mV	320uV	20	70				***************************************		±0.4
100mV	100uV	20	80						±0.4
100mV	32uV	20	90		***************************************	white-			±0.4
100mV	320mV	20	10						±1.0
100mV	1000mV	20	0			*****************	***************************************		±1.0

^{*} Data from Calibration Certificate.

Table 4-9. Performance Test Record (8 of 9)

Paragraph 4-14

		_	DE ACCURACY - utput +13dBm,			
Attenuator A Setting	Attenuator 'A' Cal Data (A)*	Channel A Input Level (L) = (13-A)	Display 1 Reading (D)	Measurement Error (E) = (L-D)	Limits	Rear Panel Output 1
20dB 10dB 0dB 30dB 40dB 50dB 60dB 70dB					±0.3 ±0.6 ±0.6 ±0.3 ±0.3 ±0.3 ±0.4 ±0.6	

^{*} Data from Calibration Certificate.

			DE ACCURACY - utput +13dBm, :			
Attenuator B Setting	Attenuator 'B' Cal Data (B)*	Channel B Input Level (L) = (13-B)	Display 2 Reading (D)	Measurement Error (E) = (L-D)	Limits	Rear Panel Output 2
20dB 10dB 0dB 30dB 40dB 50dB 60dB					±0.3 ±0.6 ±0.6 ±0.3 ±0.3 ±0.3	
70dB		EXACTS CHICAGO HARA AND AND AND AND AND AND AND AND AND AN			±0.6	**************************************

^{*} Data from Calibration Certificate.

Table 4-10. Performance Test Record (9 of 9)

Paragraph 4-15

SWR MEAS	JREMENT	
Measured SWR Channel A Channel B		Specification
	***************************************	<1.15
44CB+SHYM I-98CMA AVAINIPADA AMARINA SHEARING SHE SHE		<1.45
	Measur	

Note: The condition of the connectors and the quality of the connections in the measurement system (adaptors, cables, 50 ohm Tees, terminations, twists in the probe cables or loose cable connections, etc) can dramatically affect the accuracy of the measurement. Connection quality determines directivity and match, which in turn determines measurement accuracy.

Adjustments

Section 5

5-1 INTRODUCTION

This section describes the adjustment procedures required to enable the HP 8508A Vector Voltmeter mainframe or the HP 70138A MMS Vector Voltmeter module with the HP 85081B High Impedance Input Module to meet the specifications listed in Table 1-2 of this manual. Adjustments should only be made after determining that the instrument is out of calibration or if a repair has been carried out.

5-2 WARM-UP TIME

The HP 8508A or HP 70138A Vector Voltmeter with HP 85081B must be switched on for a minimum of 30 minutes before carrying out any adjustments. This allows the instrument to reach a stable operating temperature.

5-3 SAFETY CONSIDERATIONS

WARNING

PROCEDURES DESCRIBED IN THIS SECTION ARE PERFORMED WITH THE MAINFRAME PROTECTIVE COVERS REMOVED AND POWER SUPPLIED TO THE INSTRUMENT. SERVICING SHOULD ONLY BE PERFORMED BY TRAINED PERSONNEL WHO ARE AWARE OF THE HAZARDS INVOLVED.

Anti-Static Precautions

The printed circuit board contained in this instrument has components and devices which are susceptible to damage by electrostatic discharge (ESD). To minimize the risks of damaging or decreasing the reliability of the instrument, the following procedures and cautions should be observed when servicing the instrument.

Static-free Workstation

All servicing should be carried out at a static-free workstation whenever practical.

De-soldering

When de-soldering components, ensure that the soldering iron is grounded. Always use a metalized solder remover.

Anti-Static Freezer Spray

When attempting to locate a temperature related fault, use only an approved anti-static freezer spray.

Anti-Static Products

Table 5-1 contains details of anti-static products which are available from Hewlett-Packard.

Table 5-1. Anti-Static Products

Product	HP Part Number
Anti-static workstation kit	9300-0792
Metalized Solder Remover	8690-0227
Wrist-strap and cord	9300-0970

5-4 EQUIPMENT REQUIRED

All adjustment procedures contain a list of required test equipment. The test equipment is also identified by callouts in the test setup diagrams, where included. If substitutions must be made for the specified test equipment, refer to the Recommended Test Equipment table in the HP 8508A Vector Voltmeter mainframe manual or the HP 70138A MMS Vector Voltmeter module manual for the minimum specifications. It is important that the test equipment meet the critical specifications listed in the table if the Vector Voltmeter and the HP 85081B Input Module are to meet their performance requirements.

Note: Use a non-metalic tool whenever possible (HP Part Number 8830-0024).

When performing the adjustments to an HP 85081B which is contained in an HP 70138A MMS Vector Voltmeter, a module extender (HP Part Number 08508-60032) is required.

5-5 POST REPAIR ADJUSTMENTS

In the event of a module repair, it will be necessary to carry out all the adjustments as listed in Table 5-2.

5-6 RELATED ADJUSTMENTS

Several of the HP 85081B adjustments are interdependent and isolated adjustments should not be attempted. Because of their interactive nature, the adjustments for SRD Bias, Channel Bias, and Delay should be checked at least twice.

5-7 ADJUSTABLE COMPONENTS

Table 5-2 lists all adjustable components in the HP 85081B High Impedance Input Module.

Table 5-2. Adjustable Components

Reference	Adjustment	Adjustment
Designator	Name	Paragraph
R32 R10/R110 R15/R115 R3/R103 R38 DD 01	SRD Bias Channel A and B Symmetry Channel A and B Bias Channel A and B Gain LF Phase Delay Line	5-11 5-12 5-14 5-14 5-15 5-16

5-8 ACCESS TO THE ADJUSTMENTS

Before starting the adjustment procedures, it will be necessary to remove the instrument covers, or install an extender so that the adjustments can be readily accessed.

HP 8508A Vector Voltmeter

Remove the instrument top cover. The HP 85081B adjustments can now be accessed. NOTE: Adjust all potentiometers to their mid-position. This will minimize time to converge.

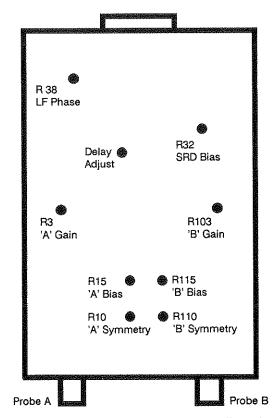


Figure 5-1. Input Module Adjustment Locations

HP 70138A MMS Vector Voltmeter

Install an MMS Module Extender (HP part number 70001-60013) in the HP 70001A Mainframe and install the HP 70138A in the extender. There are two ways to access to the HP 85081B adjustments.

1. Install the HP 85081B into the HP 70138A MMS Vector Voltmeter. Access to the HP 85081B adjustments is through the holes provided in the A5 Processor and A6 Power Supply Assemblies on the right-hand side of the HP 70138A.

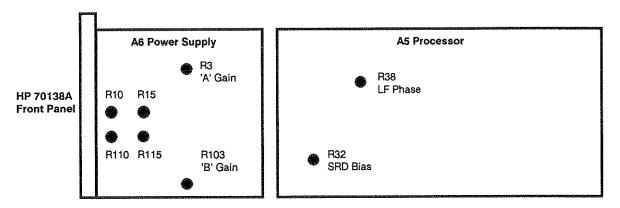


Figure 5-2. Input Module Adjustment Access Points in the HP 70138A

2. Install an Input Module Extender (HP part number 08508-60032) in the HP 70138A. Connect the HP 85081B to the extender, The HP 85081B adjustments are directly accessible.

NOTE: Adjust all potentiometers to their mid-position. This will minimize time to converge.

5-9 GENERAL TEST EQUIPMENT LIST

Instrument	Recommended Model
Signal Source	HP 8642B
Power Divider	HP 11636A
Power Meter	HP 436A/HP 437A/HP 438A
Power Sensor	HP 8482A
Oscilloscope 1GHz	HP 54100D
50ohm Termination (2)	HP 909C
50ohm Tee (2)	HP 11536A
10dB Attenuators (2)	HP 8491A/B

If substitutions must be made for the specified test equipment, refer to the Recommended Test Equipment table in Section 1 of the HP 8508A and HP 70138A Vector Voltmeter manuals for the minimum specifications. It is important that the test equipment meet the critical specifications listed in the table if the appropriate Vector Voltmeter and the HP 85081B High Impedance Input Probe are to meet their requirements.

NOTE: Use a non-metallic adjustment tool whenever possible (HP part number 8830-0024).

5- 10 GENERAL TEST EQUIPMENT SET-UP

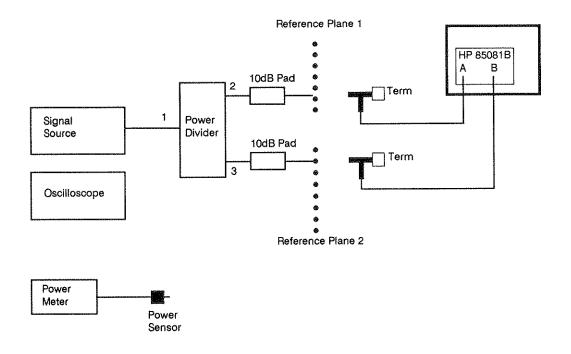


Figure 5-3. General Test Setup

5- 11 SRD Bias Adjustment

DESCRIPTION

The SRD bias is adjusted for a minimum reading in the UHF amplitude response.

PROCEDURE

- 1. Configure the equipment as shown in Figure 5-3, with the HP 85081B installed in either an HP 8508A or HP 70138A Vector Voltmeter mainframe.
- 2. Connect the Channel A 50ohm Tee to the 10dB attenuator at Reference Plane 1. Connect the Channel B 50ohm Tee to the 10dB attenuator at Reference Plane 2.
- 3. On the signal generator:

Frequency 1.0GHz Level 9.0dBm.

4. HP 8508A Setup HP 70138A Setup

Function:

[PRESET]

[I-P]

Instrument preset.

[LOCK RANGE] [SHIFT][VIEW RANGE] 'up'/'down' arrow keys

to select 1000-2000MHz

[Lock Range][1-2GHz]

Select 1-2GHz frequency range.

5. Adjust R32 (refer to Figure 5-1) to obtain a maximum reading on DISPLAY 1. NOTE: Adjustment of R32 changes the calibration settings for the entire HP 85081B.

5-12 Channel A and B Symmetry Adjustments

DESCRIPTION

Minimises the residual signal at the A and B probe tips.

PROCEDURE

- 1. Configure the equipment as shown in Figure 5-3. Separate the Channel A probe from the Channel A 500hm Tee (being careful to observe proper static control procedures). Connect the Channel A probe to the oscilloscope channel 1 input using the probe-to-BNC adaptor (HP 10218A).
- 2. Separate the Channel B probe from the Channel B 50ohm Tee (being careful to observe proper static control procedures). Connect the Channel B probe to the oscilloscope channel 1 input using the probe-to-BNC adaptor (HP 10218A).
- 3. On the oscilloscope:

Display	Alt
Sweep Speed	1us/div
Vertical Sensitivity	20mV/div
Input Coupling	50ohm
Triggering	as required

4.	HP 8508A setup	HP 70138A setup	Function

[PRESET] [I-P] Instrument preset.

[LOCK RANGE] [Lock Range][1-2GHz] Select 1-2GHz frequency range.

[SHIFT][VIEW RANGE]

[Adaptation of the content of the conte

Instrument calibration.

'up'/'down' arrow keys to select 1000-2000 MHz

[SHIFT][CAL TEST]

[Misc][CAL]

- 5. Adjust R10 (Channel A symmetry) for a minimum symmetrical amplitude signal about the oscilloscope channel 1 trace.
- 6. Adjust R110 (Channel B symmetry) for a minimum symmetrical amplitude signal about the oscilloscope channel 2 trace.

NOTE: An inability to null out the residual signal indicates that there is sampler probe damage.

- 7. Reconnect the Channel A probe to the Channel A 50ohm Tee.
- 8. Reconnect the Channel B probe to the Channel B 50ohm Tee.

5-13 Power Level Measurements

DESCRIPTION

The power level at each reference plane is noted at frequencies of 50MHz and 1GHz and will be used in all subsequent measurements.

PROCEDURE

- 1. Connect the power sensor to the 10dB attenuator at Reference Plane 1. Connect the Channel B 50ohm Tee to the 10dB attenuator at Reference Plane 2.
- 2. On the signal generator:

Frequency

50 MHz

Output level

9.0dBm

3. Note the power meter reading. (Record this reading as P1 in the power meter record table located at the rear of this section.) This reading will be used in each of the subsequent Channel A tests at 50MHz (approx -7dBm).

NOTE: When making power meter measurements, it is essential that the power meter calibration factor is correct for the frequency being measured.

4. On the signal generator:

Frequency

1GHz

Output level

9.0dBm

- 5. Note the power meter reading. (Record this reading as P2 in the power meter record table located at the rear of this section.) This reading will be used in each of the subsequent Channel A tests at 1GHz (approx -7dBm).
- 6. Connect the power sensor to the 10dB attenuator at Reference Plane 2. Connect the Channel A 50ohm Tee to the 10dB attenuator at Reference Plane 1.
- 7. On the signal generator:

Frequency

50 MHz

Output level

9.0dBm

- 8. Note the power meter reading. (Record this reading as P3 in the power meter record table located at the rear of this section.) This reading will be used in each of the subsequent Channel B tests at 50MHz (approx -7dBm).
- 9. On the signal generator:

Frequency

1GHz

Output level

9.0dBm

10. Note the power meter reading. (Record this reading as P4 in the power meter record table located at the rear of this section.) This reading will be used in each of the subsequent Channel B tests at 1GHz (approx -7dBm).

5-14 (a) Channel A and B Adjustments (Channel A and B Bias Adjustments)

DESCRIPTION

The bias level is adjusted for optimum flatness of the A and B Channel high frequency amplitude. Nominally 0.6dB referred to 50MHz.

PROCEDURE

1. Connect the Channel A 50ohm Tee to the 10dB attenuator at Reference Plane 1. Connect the Channel B 50ohm Tee to the 10dB attenuator at Reference Plane 2.

50MHz

9.0dBm

2. On the signal generator:

Frequency Level

Function: HP 70138A Setup: 3. HP 8508A Setup:

Instrument preset [PRESET] [I-P]

[B][POWER MEAS] [Mag/Ph Measure] dBm Magnitude in both displays [DISPLAY] dB [DISPLAY 2][B]

[Format Functn] [UNITS dB]

[LOCK RANGE] [Lock Range] [50-80MHz] Select 50-80 MHz frequency range

[SHIFT] [VIEW RANGE] 'up'/'down' arrow keys to select 50-80MHz

Frequency

Level

Instrument calibration [SHIFT][CAL TEST] [Misc][CAL]

[Ref][SAVE REF] Normalizes instrument [SHIFT][SAVE REF]

1GHz

9.0dBm

4. On the signal generator:

select 50-80MHz

5. Function:

HP 70138A Setup: HP 8508A Setup:

[Lock Range] [50-80MHz] Select 50-80 MHz frequency range [LOCK RANGE] [SHIFT] [VIEW RANGE] 'up'/'down' arrow keys to

Instrument calibration [SHIFT][CAL TEST] [Misc][CAL]

- 6. Adjust R15 for a reading of +A (obtained from the power meter record table at the end of the Adjustments section) in DISPLAY 1.
- 7. Adjust R115 for a reading of +B (obtained from the power meter record table at the end of the Adjustments section) in DISPLAY 2.

NOTE: The values of A and B are the compensated value taking account of signal level variations at the two frequencies, the tracking error of the power divider and the accuracy of the two attenuators.

5-14 (b) Channel A and B Adjustments (Channel A and B Gain Adjustments)

DESCRIPTION

The Channel A and B gain adjustments set up the overall absolute gain of the A and B channels.

PROCEDURE

- 1. Connect the Channel A 50ohm Tee to the 10dB attenuator at *Reference Plane 1*. Connect the Channel B 50ohm Tee to the 10dB attenuator at *Reference Plane 2*.
- 2. On the signal generator:

		Frequency Level		50 MHz 9.0 dBm	
3.	HP 8508A Setup	p	HP 70138A	Setup	Function
	[PRESET]		[I-P]		Instrument preset
	[B][POWER M [DISPLAY] dB	•	[Mag/Ph M [DISPLAY 2 [Format Ful [UNITS dB]] [B] nctn]	dBm magnitude in both displays
	[LOCK RANGI [SHIFT][VIEW 'up'/'down' arro to select 50-80M	' RANGE] ow keys	[Lock Range	e][50-80MHz]	Select 50-80MHz frequency range
	[SHIFT][CAL 7	TEST]	[Misc][CAL]	Instrument calibration

- 4. Using the readings recorded in the power meter record contained at the rear of the Adjustments section, adjust R3 (Channel A Gain) until the reading in DISPLAY 1 is the same as P1 (Channel A power level at 50MHz).
- 5. Using the readings recorded in the power meter record contained at the rear of the Adjustments section, adjust R103 (Channel B Gain) until the reading in DISPLAY 2 is the same as P3 (Channel B power level at 50MHz).

Because of the interactive nature of the adjustments, it will be necessary to repeat Section 5-14 until no further adjustments are required.

6. HP 8508A Setup HP 70138A Setup Function

[SHIFT][CAL TEST] [Misc][CAL] Instrument calibration

7. Check that the TEST OUTPUT LED extinguishes.

5-15 Set up the Module Phase Adjustment

DESCRIPTION

This adjustment is controlled by an internal test routine which will affect the phase readings at all frequencies.

PROCEDURE

- 1. Connect the Channel A 50ohm Tee to the 10dB attenuator at *Reference Plane 1*. Connect the Channel B 50ohm Tee to the 10dB attenuator at *Reference Plane 2*.
- 2. On the signal generator

	Frequency Level	50 MHz 9.0dBm	
3.	HP 8508A Setup	HP 70138A Setup	Function
	[PRESET]	[I-P]	Instrument preset
	[SHIFT] [POWER MEAS]	[Misc] [7] [0] [1] [3] [8] [Misc] [selftst menu]	Instrument into self-test setup mode.
	'up'/'down' arrow keys to select test "6"	'up'/'down' arrow keys to select test "6"	Setup code for test 6.
	[HOLD VALUE]	[Misc] [TEST ON]	Runs test.

4. HP 8508A: DISPLAY 1 should show the characters HI (this is the identification for the HP 85081B High Impedance Input Module). If other characters are displayed, adjust R38 until the display shows the characters HI in DISPLAY 1.

HP 70138A: At the right hand of the MMS screen, the lower display should show the characters HI (this is the identification for the HP 85081B High Impedance Input Module). If other characters are displayed, adjust R38 until the characters HI appear.

5. HP 8508A: Adjust R38 for a reading of 0.0 in DISPLAY 2, and HI in DISPLAY 1. Select [HOLD VALUE] to cancel the test.

HP 70138A: Adjust R38 for a reading of 0.0 in the upper display at the right-hand side of the MMS screen, and a reading of HI in the lower display. Select [Misc] [TEST OFF] to cancel the test.

5-16 Delay Line Adjustment (Phase vs Frequency)

DESCRIPTION

This adjustment compensates for the differences in electrical length of the probes and cables.

PROCEDURE

- 1. Connect the Channel A 500hm Tee to the 10dB attenuator at *Reference Plane 1*. Connect the Channel B 500hm Tee to the 10dB attenuator at *Reference Plane 2*.
- 2. On the signal generator

Frequency 50 MHz Level 9.0dBm

3. HP 8508A Setup HP 70138A Setup Function

[PRESET] [I-P] Instrument preset

[B-A PHASE] [Mag/Ph Measure] DISPLAY 1 - Magnitude [DISPLAY 2] [B-A PHASE] DISPLAY 2 - Phase

[LOCK RANGE] [Lock Range] [50 -80MHz] Select 50-80MHz frequency range [SHIFT] [VIEW RANGE]

'up'/'down' arrow keys to select 50-80MHz

[SHIFT] [CAL TEST] [Misc] [CAL] Instrument calibration

[SHIFT] [SAVE REF] [Ref] [SAVE REF] Normalizes instrument

- 4. Disconnect the Channel A 50ohm Tee and connect the power sensor to the 10dB attenuator at *Reference Plane 1*. Connect the Channel B 50ohm Tee to the 10dB attenuator at *Reference Plane 2*.
- 5. On the signal generator

Frequency 1GHz Level 9.0dBm

6. Using the readings recorded in the power meter record contained at the rear of the Adjustments section, adjust the signal generator output level to produce a power level equal to the value of P1 (Channel A power at 50MHz).

NOTE: When making power meter measurements, it is essential that the power meter calibration factor is correct for the frequency being measured.

7. Disconnect the power sensor and connect the Channel A 50ohm Tee to the 10dB attenuator at Reference Plane 1.

8. HP 8508A Setup HP 70138A Setup

[LOCK RANGE] [Lock Range] [1-2GHz] Select 1-2GHz frequency range

Function

[SHIFT] [VIEW RANGE]
'up'/'down' arrow keys
to select 1-2GHz

[SHIFT] [CAL TEST] [Misc] [CAL] Instrument calibration

9. Note the reading in DISPLAY 2. If this reading is within the range ± 1.0 Deg changes to the delay adjustment will not be necessary. The delay line adjustment is complete and the entire adjustment procedure should be repeated from Section 5-11 until the results are stable and no further adjustments are required. However, if the reading is greater than ± 1.0 Deg, continue with the procedure.

NOTE: Twists in the probe cables, or rotating the probes in the adaptors, could affect phase readings.

Before proceeding with the delay adjustment process, it will be necessary to determine exactly how access will be made to the adjustment. There are several possibilities depending upon whether an HP 8508A or HP 70138A Vector Voltmeter mainframe is being used.

Access to the Delay Adjustment

HP 8508A Vector Voltmeter procedure:

Install the HP 85081B in the HP 8508A Vector Voltmeter mainframe. Remove the bottom cover from the HP 8508A. Stand the HP 8508A on its right side. The delay adjuster is is now accessible through the 6mm hole in the bottom of the HP 8508A. Continue with the procedure from step 8.

In some instruments, this hole may not have been provided. To add the hole to the HP 85081B Input Module compartment baseplate, refer to the location diagram shown below.

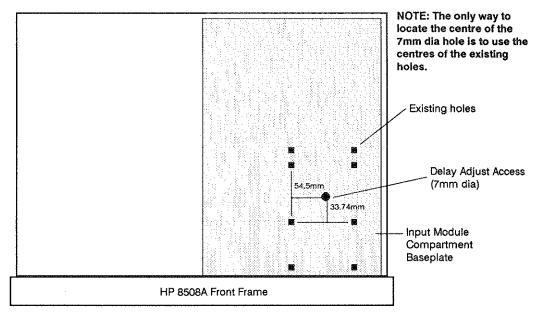


Figure 5-4. Delay Adjust Access Location

The alternative process is to extend the HP 85081B Input Module from the HP 8508A Vector Voltmeter mainframe using a module extender (HP part number 08508-60032). Access to this adjustment is readily available.

HP 70138A Procedure:

In this case, the HP 85081B Input Module should be used with the module extender (HP part number 08508-60032). Access to the delay adjustment is readily available.

- 10. Repeat steps 1 through 9 (with the HP 85081B installed for access to the delay adjustments).
- 11. Adjust the Delay Adjuster (DD01) for a reading of '0' in DISPLAY 2.
- 12. Interchange the probe Tees and note the new phase reading in DISPLAY 2.
- 13. The delay adjuster should now be adjusted for a reading equivalent to half the value obtained in step 12.
- 14. The adjustment is now complete.

After completing this adjustment, repeat the entire Module Adjustment procedure from Section 5-11 until the results are stable.

Table 5-3. Power Meter Readings Record

POWER METER READINGS (taken in Section 5-13)
Reference	Power Level (dBm)
P1 (Channel A power at 50MHz)	
P2 (Channel A power at 1GHz)	
P3 (Channel B power at 50MHz)	
P4 (Channel B power at 1GHz)	

Calculate the value that DISPLAY 1 will be adjusted for and record as A.

Calculate the value that DISPLAY 2 will be adjusted for and record as B.

Replaceable Parts

Section 6

6-1 INTRODUCTION

This section contains information for ordering parts. Table 6-2 lists the abbreviations used in the parts list and throughout the manual. Table 6-3 lists all replaceable parts in reference designator order and Table 6-4 lists the names and addresses that correspond to the manufacturer's code number used in the parts list.

6-2 ABBREVIATIONS

Table 6-2 lists all the abbreviations used in the parts lists and throughout the manual. In some cases, two forms of an abbreviation are given, one in all capital letters and the other in partial or no capital letters. This is because the abbreviations used in the parts list are always all capitals; however, in other parts of the manual, abbreviations are used in partial or no capital letters.

6-3 REPLACEABLE PARTS LIST

Table 6-3 is organized as follows:

- (a) Electrical assemblies and their components in alpha-numeric order followed by reference designation.
- (b) Chassis-mounted parts in alpha-numeric order by reference designation.
- (c) Miscellaneous parts.

The information given for each part consists of the following:

- (a) The Hewlett-Packard part number.
- (b) Part number check digit (CD).
- (c) The total quantity (QTY) in the instrument.
- (d) The description of the part.
- (e) A typical manufacturer of the part (in a five-digit code).
- (f) The manufacturer's part number for that part.

The total quantity for each part is given only once - at the first appearance of the part in the list.

6-4 ORDERING INFORMATION

To order a part listed in the replaceable parts list table, quote the Hewlett-Packard part number (with the check digit), indicate the quantity required, and address the order to the nearest Hewlett-Packard office. The check digit will ensure accurate and timely processing of your order.

To order a part that is not listed in the Replaceable Parts table, include the instrument model number, instrument serial number, the description and function of the part, and the number of parts required. Address the order to the nearest Hewlett-Packard office.

6-5 DIRECT MAIL ORDER SYSTEM

Within the USA, Hewlett-Packard can supply parts through a direct mail order system. Advantages of using the system are as follows:

- (a) Direct ordering and shipment from the HP Parts Centre in Roseville, California.
- (b) No maximum or minimum order value on any mail order (there is a minimum order amount for parts ordered through a local HP office when the orders require billing and invoicing).
- (c) Prepaid transportation (there is a small handling charge for each order).
- (d) No invoices to provide these advantages, a cheque or money order must accompany each order.

Mail order forms and specific ordering information are available through your local HP office. Addresses and phone numbers are located at the back of this manual.

REFERENCE DESIGNATIONS

A assembly
AT attenuator; isolator;
termination
B fan: motor
BT battery
C capacitor
CP coupler
CR diode; diode
thyristor; varactor
DC directional coupler
DL delay line
DS annunciator:
signaling device
(audible or visual):
lamp; LED
iamp, ces

E miscellaneous
electrical part
Ffuse
FL filter
H hardware
HY circulator
J electrical connector
(stationary portion);
ack
Krelay
L coil; inductor
M meter
MP miscellaneous
mechanical part
•

P electrical connector (movable portion);
plug
Q transistor; SCR;
triode thyristor; FET
R resistor
RT thermistor
S switch
T transformer
TB terminal board
TC thermocouple
TP test point

Table 6-2. Abbreviations (1 of 2)

ABBREVIATIONS

A	ampe
ACCEC	alternating curre
AUCES	S accesso
ADJ	adjustme
	analog-to-digit
	audio frequenc
AFC	automat
	frequency control
AGC	automatic ga
	control
	aluminu
ALC	automatic lev
	control
AM	amplitude modulatio
AMPL.	amplific
APC .	automatic phas
	control
ASSY	assemb
AUX .	auxilia
avg	averaç
AWG	American wi
	gauge
BAL	balanc
BCD	binary code
	decimal
80	boa
BECH	beryllium coppe
	beat frequence
DI .	oscillator
8H	binder hea
	breakdow
BP	ureakGOW
PP	bandpas
	bandpass filte
	bras
BWO	backware-way
e	oscillator
	calibra
	counter-clockwis
	ceram
	chann
	centimete
CMO	cabinet mount on
	coaxí

COEF coefficient COM common
COMP composition
COMPL complete
CONTE
CONN connector
CP cadmium plate
CRT cathode-ray tube
CTL complementary
transistor logic
CW continuous wave
cw cłockwise
cm centimeter
D/A digital-to-analog
dB decibel
dBm decibel referred
dBm decibel referred to 1 mW
dc direct current
deg degree (temperature
interval or difference)
° degree (plane
angle)
°C degree Celsius
(centiorade)
(centigrade) °F degree Fahrenheit
°F degree Fahrenheit
°F degree Fahrenheit °K degree Kelvin
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list)
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole,
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR degree Fahrenheit deposite Fahrenheit detector diameter (used in parts list) DIFF AMPL differential amplifier
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband DTL diode transistor
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband DTL diode transistor iogic
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband DTL diode transistor logic DVM digital voltmeter
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband DTL diode transistor logic DVM digital voltmeter ECL emitter coupled
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband DTL diode transistor logic DVM digital voltmeter ECL emitter
°F degree Fahrenheit °K degree Kelvin DEPC deposited carbon DET detector diam diameter DIA diameter (used in parts list) DIFF AMPL differential amplifier div division DPDT double-pole, double-throw DR drive DSB double sideband DTL diode transistor logic DVM digital voltmeter ECL emitter coupled

10.6.4.1.0.0
EDP electronic data
EDP electronic data processing ELECT electrolytic
ELECT electrolytic
ENGAP encapsulated
EXT external
Ffarad FET field-effect transistor
FET field-effect transistor
F/F flip-flop FH flat head
FH flat head FIL H fillister head
FM frequency modulation
FP front panel
FREQ frequency
FXD fixed
g gram GE germanium
GHz gigahertz
GL glass
GRD ground(ed)
Hhenry
h hour HET heterodyne HEX hexagonal
HEX hexagonal
HD head
HDW hardware
HF high frequency
HG mercury
HIhigh
HP Hewlett-Packard
HPF high pass filter HR hour (used in
parts list)
HVhigh voltage
Hz Hertz
IC integrated circuit
ID inside diameter
IF intermediate
frequency
IMPG impregnated
in incandescent INCL include(s)
INPinclude(s)
INS insulation

INT internal
kg kilogram
kHz kilohertz
kkilohm
kV kilovolt
lbpound
LC inductance-
capacitance
LED light-emitting diode
LF low frequency
LG long
LHleft hand
LIM limit
LIN linear taper (used
in parts list)
LK WASH lock washer
LO low; local oscillator
LOG logarithmic taper
(used in parts list)
log logarithm(ic)
LPFlow pass filter
loglogarithm(ic) LPFlow pass filter LVlow voltage
m meter (distance)
mA milliampere
MAX maximum
M megohm
MEG meg (10 ⁶) (used
in parts list)
MET FLM metai film MET OX metaliic oxide
MET OX metallic oxide
MF medium frequency;
microfarad (used in
parts list)
MFR manufacturer
mg milligram
MHz, megahertz
mH millihenry
mho mho
min minute (time)
' minute (plane angle)
MINAT miniature
1979/PHILL

NOTE

All abbreviations in the parts list will be in upper-case.

MOD modulator	OD outside diameter	PWVpeak working	TD time de
MOM momentary	OH oval head	voltage	TERM termi
MOS metal-oxide	OP AMPL operational	RC resistance-	TFT thin-film transis
semiconductor	amplifier		
		capacitance	TGL tog
ms millisecond	OPT option	RECT rectifier	THD thre
MTG mounting	OSC oscillator	REFreference	THRU throu
MTR meter (indicating	OXoxide	REG regulated	TI titani
device)	OZounce	REPL replaceable	TOL tolerar
mV millivolt	Ω ohm	RF radio frequency	TRIM trimr
mVac millivolt, ac	P peak (used in parts	RFI radio frequency	TSTR transis
mVdc millivoit, dc	list)	interference	TTL transistor-transis
mVpk millivolt, peak	PAM puise-amplitude	RH round head; right hand	logic
mVp-p , , millivolt, peak-	modulation	RLC resistance-	TV televis
to-peak	PC printed circuit	inductance-	TVI television interfere
mVrms millivolt. rms	PCM pulse-code modula-		
		capacitance	TWT traveling wave to
mW milliwatt	tion; pulse-count	RMO rack mount only	U , micro (10 ⁻⁶) (us
MUX multiplex	modulation	rms root-mean-square	in parts list)
MY mylar	PDM pulse-duration	RNDround	UF microfarad (used
μA microampere	modulation	ROM read-only memory	parts list)
μF microfarad	pF picofarad	R&P rack and panel	UHF ultrahigh freque
μΗ microhenry	PH BRZ phosphor bronze	RWV reverse working	UNDEF undefin
umho micromho	PHL Phillips	voltage	UNREG unrequia
μs microsecond	PIN positive-intrinsic-	S scattering parameter	V
μV microvolt	negative	s second (time)	VA voltamp
μVac microvolt, ac	PIV peak inverse voltage	" second (plane angle)	
μVdc microvolt, dc			Vacvolts,
	pk peak	S-B slow-blow (fuse)	VAR varia
μVpk microvolt, peak	PL phase lock	(used in parts list)	VCOvoltage-control
μVp-p microvolt, peak-	PLO phase lock oscillator	SCR silicon controlled	oscillator
to-peak	PM phase modulation	rectifier; screw	Vdcvolts,
μVrms microvolt, rms	PNP positive-negative-	SE selenium	VDCW volts, dc, work
μW microwatt	positive	SECT sections	(used in parts list)
nAnanoampere	P/O part of	SEMICON semiconductor	V(F) volts, filte
NC no connection	POLY polystyrene	SHF superhigh frequency	VFO variable-freque
N/C normally closed	PORC porcelain	SI silicon	oscillator
NEneon	POS positive; position(s)	SIL silver	VHF very-high freque
NEG negative	(used in parts list)	SL slide	Voic very-ingri ireque
nF nanofarad			Vpk volts, po
	POSN position	SNR signal-to-noise ratio	Vp-p volts, peak-to-pe
NI PL nickel plate	POT potentiometer	SPDT single-pole,	Vrms voits, r
N/O normally open	p-p peak-to-peak	double-throw	VSWR voltage stand
NOM nominal	PP peak-to-peak (used	SPG spring	wave ratio
NORMnormal	in parts list)	SR split ring	VTO voltage-ti
NPN negative-positive-	PPM pulse-position	SPST single-pole.	oscillator
negative	modulation	single-throw	VTVM vacuum-ti
NPO negative-positive	PREAMPL preamplifier	SS Service Sheet	voltmeter
zero (zero tempera-	PRF pulse-repetition	SSB single sideband	V(X) voits, switch
ture coefficient)	frequency	SST stainless steel	W
NRFR not recommended			
	PRR pulse repetition rate	STL steel	W/v
for field replacement	os picosecond	SQsquare	WIV working inve
NSRnot separately	PT point	SWR standing-wave ratio	voltage
replaceable	PTM pulse-time	SYNC synchronize	WW wirewor
ns nanosecond	modulation	T timed (slow-blow fuse)	W/O with
nWnanowatt	PWM pulse-width	TA, tantalum	YIG yttrium-iron-gar
OBD, order by description	modulation	TC temperature	Z _o characterisi

NOTE

All abbreviations in the parts list will be in upper-case.

MULTIPLIERS

Abbreviation	Prefix	Multiple
T	tera	10 ¹²
G	giga	10 ⁹
M	mega	106
k	kilo	10 ³
da	deka	10
d	deci	10 ⁻¹
C	centi	10 ⁻²
m	milli	10 ⁻³
μ	micro	10 ⁻⁶
n	nano	10 ⁻⁹
р	pico	10-12
f	femto	10-15
a	atto	10-18

Table 6-3. Replaceable Parts

Reference Designation	HP Part Number	C D	Qty	Description	Mfr Code
	85081-69200	7	1	Rebuilt Hi-Z Input Module	
	85081-60300	0	2	Probe Circuit Board	
	08405-2044	9	2	Probe Insulator	
	08405-6055	6	2	Probe Barrel	
	08405-40003	8	2	Probe Tip Static Protector	
	85081-20105	9	1	Rod, Module Locking	
	85081-20107	1	1	Knob, Module Locking	
	0510-0070	7	2	Retainer, Crsnt.Ext	
	05001 00010	3	1	Ring Retaining Label - Horizontal	
	85081-00010	3		(HP 8508A System)	
	85081-00009	0	1 1	Label - Vertical	
	05001 00007		•	(HP 70138A System)	
				,	
		ł			
			ļ		
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			1		
		1			
	1		1		

Manual Changes

Section 7

7-1 INTRODUCTION

This section normally contains information for adapting this manual to instruments for which the content does not directly apply. Since this manual does directly apply to instruments having the series code listed on the title page, no change information is given here. Refer to INSTRUMENTS COVERED BY MANUAL in Section 1 for additional important information about date code and series code coverage.

Service Section 8

8-1 INTRODUCTION

The HP 85081B is not repairable to component level. Should a unit prove to be defective, it should be replaced with a rebuilt assembly (exchange unit) obtainable through your local HP Service Office.

8-2 ANTI-STATIC PRECAUTIONS

The printed circuit board of this instrument is susceptable to damage by electrostatic discharge (ESD). To minimize the risks of damaging or decreasing the reliability of the instrument, the following procedures and cautions should be observed when servicing the instrument.

Static-free Workstation

All servicing should be carried out at a static-free workstation.

De-soldering

When desoldering, ensure that the soldering iron is earthed. Always use a metalized solder remover.

Anti-static freezer spray

When attempting to locate a temperature related fault, use only an approved anti-static freezer spray.

Anti-static Products

Table 8-1 contains details of anti-static products which are available from Hewlett-Packard.

Table 8-1. Anti-Static Products

Product	HP Part No.		
Anti-static workstation kit	9300-0792		
Metalized Solder Remover	8690-0227		
Wrist-strap and cord	9300-0970		

8-3 RECOMMENDED TEST EQUIPMENT

Equipment required to troubleshoot the HP 85081B is listed in Table 1-2. Other equipment may be substituted if it meets or exceeds the critical specifications listed in the table.

8-4 TROUBLESHOOTING

GENERAL DESCRIPTION

The HP 85081B is a two-channel RF to IF convertor plug-in module that operates in the 100kHz to 1GHz frequency range. The module reconstructs two RF signals (having the same fundamental frequency) into two IF signals at a frequency of 20kHz. These re-constructed signals have the same amplitude and phase relationships of the original RF signal.

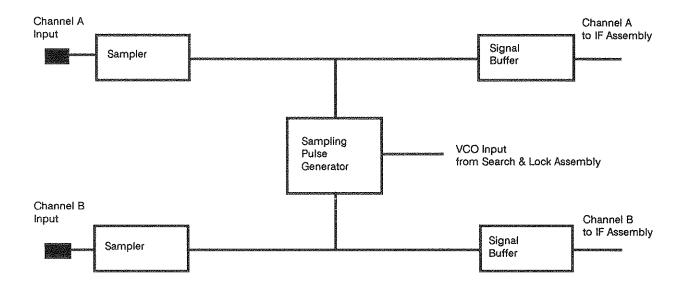


Figure 8-1. Simplified Block Diagram

The Input Module, with its associated cables and probes, form a dual-channel sampling system. The main elements of which are a Pulse Generator, two Sampling Bridges and two Signal Buffers. The sampling bridges are located in the test probes and flexible cables transfer the sampling point from the Input Module to the Probe tips.

SERVICING THE INPUT MODULE

The Input Module must be installed in either an HP 8508A mainframe or an HP 70138A MMS Vector Voltmeter before it can be tested. Should the Self Test process detect a failure in the Input Module, an appropriate Error Code in the 600 Series will be shown in DISPLAY 2 of the instrument.

TROUBLESHOOTING PROCEDURE

An HP 85081B failure will be indicated in one of two ways. Either the HP 8508A or the MMS System will display an error code in the 600 Series, or no digits will be shown in the displays.

- 1. Check that the HP 85081B is properly installed in the HP 8508A Vector Voltmeter mainframe or the HP 70138A MMS Vector Voltmeter Module. The HP 85081B could also be installed in an Input Module Extender (HP part number 08508-60032).
- 2. Cycle the instrument power.
- 3. Test the probes by performing the adjustment procedure for the probe symmetry or by checking with the CAL/TEST output on the instrument front panel. If, however, one or both probes prove to be defective, the preferred repair strategy is to replace the faulty module with a rebuilt exchange unit.
- 4. If the probes are found to be operating correctly, the Input Module Adjustment procedures should be carried out and the self tests run again.
- 5. Should the Input Module still fail the self test, it should be replaced with an exchange module.
- 6. If the HP 85081B adjustments are completed successfully, then this indicates that the problem is in either the HP 8508A Vector Voltmeter mainframe, or the HP 70138A MMS Vector Voltmeter module.

Failure of the HP 85081B adjustments indicates that the HP 85081B should be replaced.

The replacement module is already calibrated and no adjustments should be necessary when this is installed.

PROBE SAMPLER BOARD REPLACEMENT

The Sampler Assembly is mounted on a small plug-in circuit board mounted in the probe assembly, as shown below.

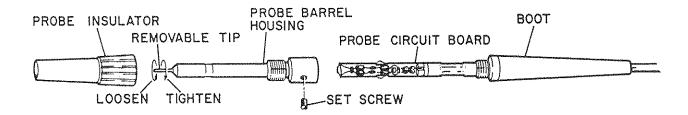


Figure 8-2. Probe Housing Assembly

NOTE: The Sampler Assembly can be easily damaged by static discharge and ESD precautions should be observed when handling this assembly.

To gain access to the Sampler Assembly, unscrew the probe insulator. Unscrew the small set screw and then the probe barrel housing. The probe circuit board can now be carefully pulled free.

When the probe circuit board is being replaced, be sure to align the board in the guides so that the connector pins mate together readily when the board is pushed gently into position. Ensure that the inside of the probe barrel is clean before re-assembly. Once assembled, the Input Module adjustment procedures should be carried out.

DISASSEMBLY AND REASSEMBLY PROCEDURES

The following operations must only be performed at an ESD protected environment.

Disassembly of the Input Module

- 1. Ensure the LINE switch is off.
- 2. Remove the HP 85081B from the Vector Voltmeter.
- 3. Place the HP 85081B on a flat surface (with the front panel towards you).
- 4. Remove the two crescent clips from the retaining rod.
- 5. Remove the retaining rod.
- 6. Remove the two screws holding the front panel to the module. Put the front panel in a safe place.
- 7. Remove the three screws exposed at the top of the module.
- 8. Turn the module over and remove the 12 screws holding the two halves of the assembly together.
- 9. The module casing can now be separated to allow access to the module circuit board assembly.

Reassembly of the Input Module

- 1. Install the circuit board and close the module casing.
- 2. Reinsert (and tighten) the 12 screws.
- 3. Turn the module over and replace the three fixing screws.
- 4. Refit the front panel and the two fixing screws.
- 5. Replace the retaining rod and the two crescent clips (HP part number 0510-0070).

The HP 85081B is now ready for operation.

